

Title (en)

A METHOD OF DEPTH ROUTING AN ELECTRONIC LAYUP AND APPARATUS FOR EFFECTING SUCH A METHOD

Title (de)

VERFAHREN ZUM TIEFENROUTING EINES ELEKTRONISCHEN LAYUP UND VORRICHTUNG ZUR DURCHFÜHRUNG SOLCH EINES VERFAHRENS

Title (fr)

PROCÉDÉ DE ROUTAGE DE PROFONDEUR D'UN EMPILEMENT ÉLECTRONIQUE ET DISPOSITIF POUR METTRE EN UVRE LE PROCÉDÉ

Publication

EP 2243341 A1 20101027 (EN)

Application

EP 08870035 A 20081209

Priority

- SG 2008000470 W 20081209
- SG 2008001828 A 20080108

Abstract (en)

[origin: WO2009088363A1] A method of depth routing an electronic layup comprised of a dielectric sandwiched between a metal layer and a metal substrate which is then laminated. The method involves first positioning a hardened mask so that the mask is interposed between the metal layer and at least one nozzle of a sandblasting machine, the mask having at least one aperture provided therein. Thereafter, the electronic layup is sandblasted through the at least one aperture by way of the sandblasting machine. The force, size and type of abrasive applied by the sandblasting machine are sufficient to erode the metal layer and the dielectric but not the substrate.

IPC 8 full level

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CPC (source: EP US)

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